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L SS L TR TY MOR R N WORL



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Under evelopment	
Mass production	

Product naming rules



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Features

imensionmmxmmxmmLong operating life
igh radiation flux
nstant light less thanns100nsLow voltageoperated
igh heat dissipation efficiency100nsSuperiorSprotectionRoS compliantRoS



Application range



UV UV Curing



UV UV Printing





UV UV Exposure



Security, Banknote

Nail Polish Curing



Mosquito Killer







Typical Optical/Electrical Characteristics @Ta=25š7[·]HmdY

Symbol	ltem	Min.	Тур	Max.	Units	Test Conditions
е	Radiation lux辐射功率				mW	m
V	orward Voltage 正向电压				V	m
Р	Peak Wavelength				nm	m
	Power ngle				deg	m
R	Reverse urrent				u	VR V
L	Life Time				our	m
L	Life Time				our	m

Absolute Maximum Ratings 绝对最大额定值@H51&)š7

Item名称	Symbol 符号	Absolute Maximum Rating 绝对最大额定值	Units
Power dissipation	Pd		W
Peak orward urrent	р		m
Reverse Voltage	V _R		V
Operating Temperature	Topr	20°C To +60°C	
Storage Temperature	Tstg	0C To +40°C	

Notes注:

- 1.Radiant flux measurement tolerance:±10%;
- 2.Forward voltage measurement tolerance:±3%;
- 3.Peak wavelength measurement tolerance:±3nm;
 - .1/10 Duty Cycle,0.1ms Pulse Width.1/10占空比, 0.1ms脉冲宽度;
- 5.The temperature of Aluminum PCB do not exceed 55℃.基板温度不超过55℃。







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Package Dimensions







Notes

Il dimension units are millimeters

2. All dimension tolerance is ±0.1mm unless otherwise noted.

Welded plate Dimensions



Notes :

When the circuit configuration is not affected suggested the increase in the middle of the copper area or the connection between the middle and the pad and the negative electrode can improve the cooling performance of the product t is recommended to use mmthickness of steel mask

mm



Label

- TYP : XXXXXXXXX
- QTY XXXXX
- V orward voltage rank
 - e Radiation lux rank

XXXX

- P Peak Wavelength
 - T XXXX

LOT NO Lot Number

1	HONGLITRONIC 鸿利光电		RoHS
TYPE: VF: IF: DATE		QTY: e: P: LOT. NO:	



SPEC NO: B-16-C-0140

REV NO: A/0





Reflow soldering instructions		
₽4 ofile Feature	Peafij Based solder	Lead-Free Solder
verage Ramp Rate Ts _{max} to Tp		
NoteNotp a Tf T]TJT T [a Tf T recommend to use a convection type reflow machine 145°-165°-185°-21	s]TJ en U [a Tf with zones 0°-220°-240°-260°-240	owig n R M at P ⊀M 90cm/min
recommend to use Lead ree Paste with a melting p 210°C - 220°C	oint between 210℃-220℃	
the reflow soldering time should not be more than ured on the surface of the package body	s all temperature means t	he temperature meas
When using hot plate the temperature is no more that	n °C the time is not m	ore than seconds
opyright uang Zhou ong Li Tronic o	. Ltd II rights reserve	d
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Use the matters needing attention(使用注意事项)			
	storage)		
		5-30 °C	60%
LED	24H		
		60 ℃±5 ℃ 12H	
To avoid moisture, we recommend storage conditions for the unopened LED $+5 \sim +30$ °C, relative hu-			

midity <60%. LED should be used within 168 Hrs. of opening the package. Please make sure to dehumidify and vacuum pack the remaining/ unused LED. Dehumidifying condition: +120 °C \pm 5 °C, 04 Hrs. Effective age for the sealed led is one year.

the assembly notes)

260 °C.

1000g

Soldering Conditions This product must be used reflow soldering practices, the maximum temperature of reflow should not exceed 220 °C.Please make sure when soldering, there is no external force on the soldering surface (such as pressure, friction or sharp metal nails, etc.), to avoid gold wire deformation or damage and other abnormalities.

If beyond recommended conditions, we cannot guarantee the LED stability, please do the risk assessment first.

anti-Static Measures)

Please take adequate measures to prevent electrostatic generation, such as wearing electrostatic ring or anti-static fingerstall etc; any relative products like plant equipment, machinery, carrier and transportation units shall be connected to discharging unit/ ground. After assembly, please make sure to discharge Static Electricity with proper ESD equipment.

temperature Control)

500V



During assembly, please ensure that a good quality thermal paste is applied and distributed evenly over the surface. While using thermal pad (Heat Sink), make sure LED is firmly tightened and there is no gap between surfaces. The need to ensure the cooling medium dielectric withstand test at least through 500V.

drive control)

rive this product at constant current Output current range specifications should be according to the operational and other conditions as mentioned in data sheet efore using a con stant voltage source or altered specifications other than recommended please consider risk factors

other)

(Cl2,H2S NH3 SOx NOx

Product is not suitable to use in following conditions;

- ---Direct or indirect wet / damp conditions, such as rain, etc;
- ----in contact with sea water and erosive materials;
- ---Exposed to corrosive gases (e.g., Cl2, H2S, NH3, SOx, NOx, etc.);
- —-Exposed to dust, liquids or oils;





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Notes注:

Il high power emitter L products mounted on aluminum metal core printed circuit board can be lighted directly but we do not recommend lighting the high power products for more than seconds without a appropriate heat dissipation equipment

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Reflow soldering should not be done more than two times. The reflow temperature we recommend is

°C,When the temperature exceeds $\hfill \hfill \hf$

°C L